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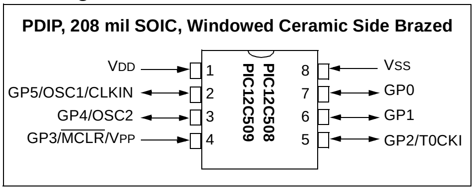
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

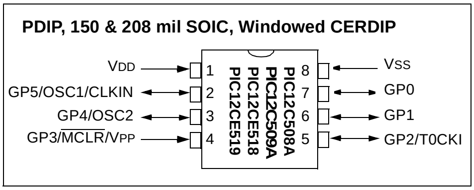
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	16 x 8
RAM Size	41 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lce519-04i-sn

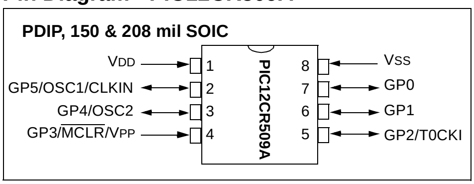
Pin Diagram - PIC12C508/509



Pin Diagram - PIC12C508A/509A, PIC12CE518/519



Pin Diagram - PIC12CR509A



Device Differences

Device	Voltage Range	Oscillator	Oscillator Calibration^2 (Bits)	Process Technology (Microns)
PIC12C508A	3.0-5.5	See Note 1	6	0.7
PIC12LC508A	2.5-5.5	See Note 1	6	0.7
PIC12C508	2.5-5.5	See Note 1	4	0.9
PIC12C509A	3.0-5.5	See Note 1	6	0.7
PIC12LC509A	2.5-5.5	See Note 1	6	0.7
PIC12C509	2.5-5.5	See Note 1	4	0.9
PIC12CR509A	2.5-5.5	See Note 1	6	0.7
PIC12CE518	3.0-5.5	-	6	0.7
PIC12LCE518	2.5-5.5	-	6	0.7
PIC12CE519	3.0-5.5	-	6	0.7
PIC12LCE519	2.5-5.5	-	6	0.7

Note 1: If you change from the PIC12C50X to the PIC12C50XA or to the PIC12CR50XA, please verify oscillator characteristics in your application.

Note 2: See Section 7.2.5 for OSCCAL implementation differences.

TABLE 5-1: SUMMARY OF PORT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on All Other Resets
N/A	TRIS	—	—							--11 1111	--11 1111
N/A	OPTION	$\overline{\text{GPWU}}$	$\overline{\text{GPPU}}$	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
03H	STATUS	GPWUF	—	PAO	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	q00q quuu(1)
06h	GPIO (PIC12C508/ PIC12C509/ PIC12C508A/ PIC12C509A/ PIC12CR509A)	—	—	GP5	GP4	GP3	GP2	GP1	GP0	--xx xxxx	--uu uuuu
06h	GPIO (PIC12CE518/ PIC12CE519)	SCL	SDA	GP5	GP4	GP3	GP2	GP1	GP0	11xx xxxx	11uu uuuu

Legend: Shaded cells not used by Port Registers, read as ‘0’, — = unimplemented, read as '0', x = unknown, u = unchanged, q = see tables in Section 8.7 for possible values.
Note 1: If reset was due to wake-up on change, then bit 7 = 1. All other resets will cause bit 7 = 0.

5.4 I/O Programming Considerations

5.4.1 BI-DIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The BCF and BSF instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a BSF operation on bit5 of GPIO will cause all eight bits of GPIO to be read into the CPU, bit5 to be set and the GPIO value to be written to the output latches. If another bit of GPIO is used as a bi-directional I/O pin (say bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Example 5-1 shows the effect of two sequential read-modify-write instructions (e.g., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

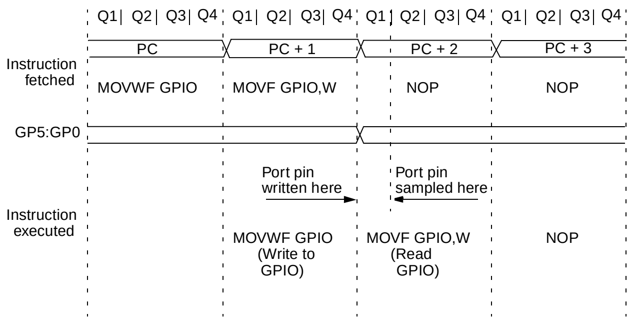
EXAMPLE 5-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial GPIO Settings
; GPIO<5:3> Inputs
; GPIO<2:0> Outputs
;
;                    GPIO latch  GPIO pins
;                    ----------  ----------
  BCF   GPIO, 5   ;--01 -ppp   --11 pppp
  BCF   GPIO, 4   ;--10 -ppp   --11 pppp
  MOVLW 007h       ;
  TRIS  GPIO      ;--10 -ppp   --11 pppp
;
;Note that the user may have expected the pin
;values to be --00 pppp. The 2nd BCF caused
;GP5 to be latched as the pin value (High).
```

5.4.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

FIGURE 5-2: SUCCESSIVE I/O OPERATION



This example shows a write to GPIO followed by a read from GPIO.

Data setup time = (0.25 T_{CY} – T_{PD})

where: T_{CY} = instruction cycle.

T_{PD} = propagation delay

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

6.0 TIMER0 MODULE AND TMR0 REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
  - Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
  - Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

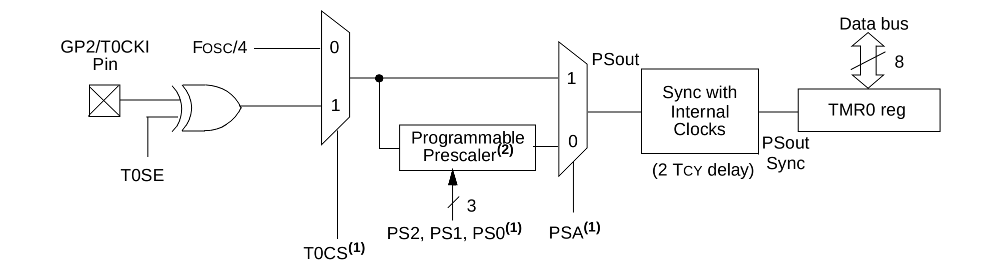
Timer mode is selected by clearing the T0CS bit (OPTION<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two instruction cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The T0SE bit (OPTION<4>) determines the source edge. Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.1.

The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 6.2 details the operation of the prescaler.

A summary of registers associated with the Timer0 module is found in Table 6-1.

FIGURE 6-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0CS, T0SE, PSA, PS2, PS1 and PS0 are located in the OPTION register.
2: The prescaler is shared with the Watchdog Timer (Figure 6-5).

6.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer (WDT), respectively (Section 8.6). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS2:PS0 bits (OPTION<3:0>) determine prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1, MOVWF 1, BSF 1,x,` etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the WDT. The prescaler is neither readable nor writable. On a RESET, the prescaler contains all '0's.

6.2.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on the fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to the WDT.

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

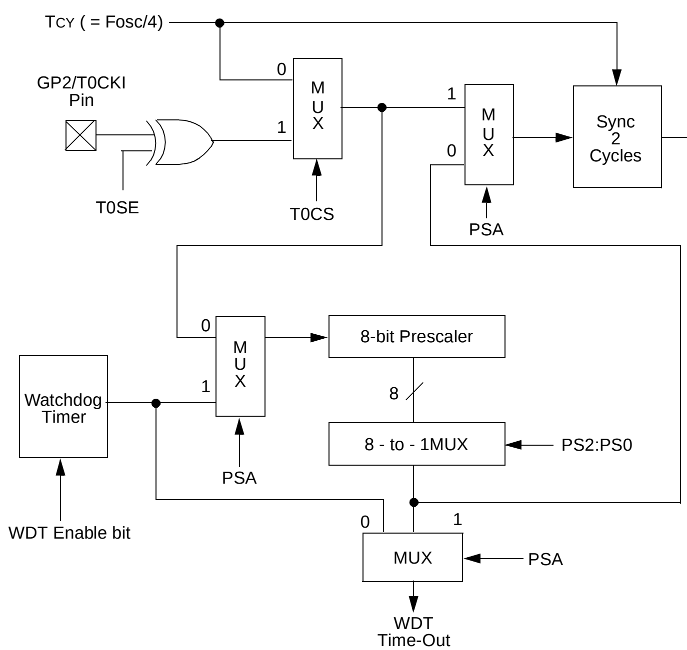
```
1.CLRWDT                  ;Clear WDT
2.CLRF   TMR0             ;Clear TMR0 & Prescaler
3.MOVLW  '00xx1111'b      ;These 3 lines (5, 6, 7)
4.OPTION                  ; are required only if
                          ; desired
5.CLRWDT                  ;PS<2:0> are 000 or 001
6.MOVLW  '00xx1xxx'b      ;Set Postscaler to
7.OPTION                  ; desired WDT rate
```

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 6-2. This sequence must be used even if the WDT is disabled. A `CLRWDT` instruction should be executed before switching the prescaler.

EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

```
CLRWDT                  ;Clear WDT and
                        ;prescaler
MOVLW   'xxxx0xxx'      ;Select TMR0, new
                        ;prescale value and
                        ;clock source
OPTION
```

FIGURE 6-5: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS2:PS0 are bits in the OPTION register.

FIGURE 7-3: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

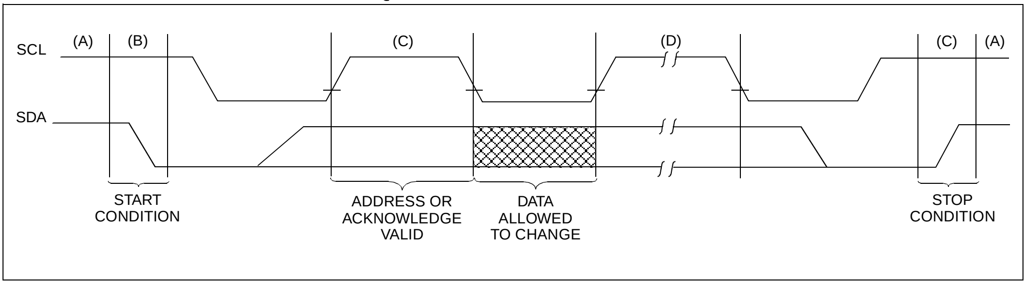
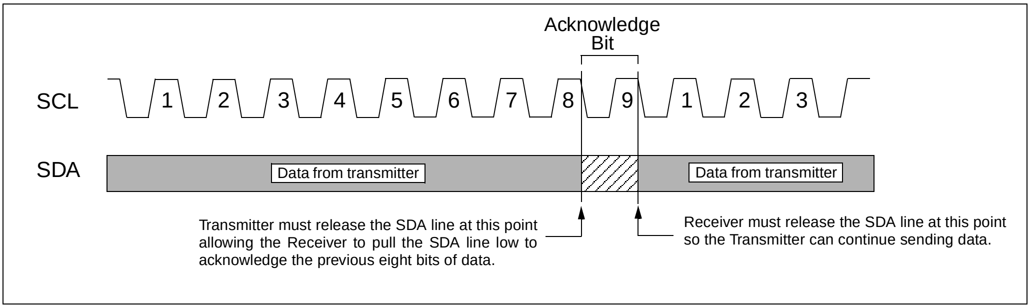


FIGURE 7-4: ACKNOWLEDGE TIMING

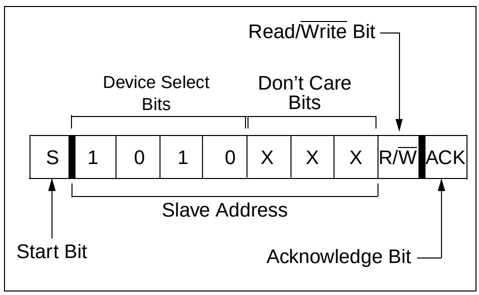


7.2 Device Addressing

After generating a START condition, the bus master transmits a control byte consisting of a slave address and a Read/$\overline{\text{Write}}$ bit that indicates what type of operation is to be performed. The slave address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one a read operation is selected, and when set to a zero a write operation is selected. (Figure 7-5). The bus is monitored for its corresponding slave address all the time. It generates an acknowledge bit if the slave address was true and it is not in a programming mode.

FIGURE 7-5: CONTROL BYTE FORMAT



8.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 8-4 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 8-4: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

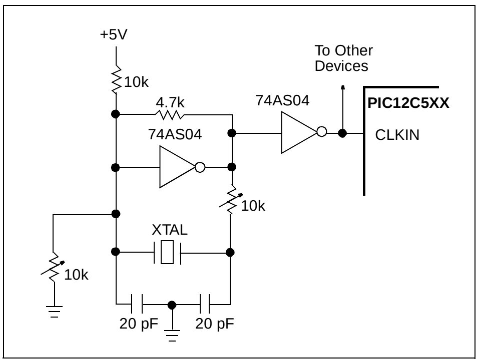
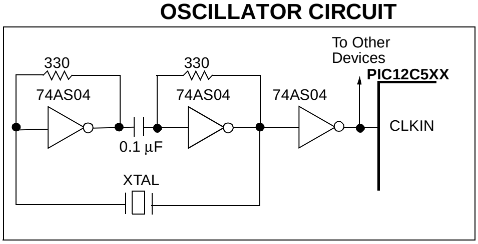


Figure 8-5 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 8-5: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



8.2.4 EXTERNAL RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used.

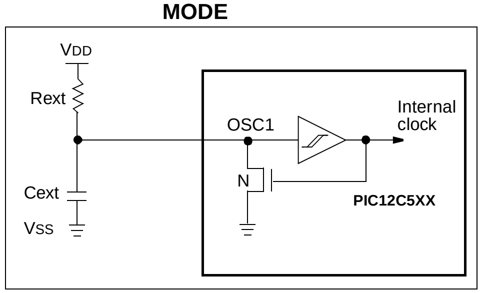
Figure 8-6 shows how the R/C combination is connected to the PIC12C5XX. For Rext values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high Rext values (e.g., 1 MΩ) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping Rext between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to VDD for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

FIGURE 8-6: EXTERNAL RC OSCILLATOR MODE



8.6.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the OPTION register. Thus, a time-out period of a nominal 2.3 seconds can be realized. These periods vary with temperature, VDD and part-to-part process variations (see DC specs).

Under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler), it may take several seconds before a WDT time-out occurs.

8.6.2 WDT PROGRAMMING CONSIDERATIONS

The `CLRWDT` instruction clears the WDT and the postscaler, if assigned to the WDT, and prevents it from timing out and generating a device RESET.

The `SLEEP` instruction resets the WDT and the postscaler, if assigned to the WDT. This gives the maximum SLEEP time before a WDT wake-up reset.

FIGURE 8-12: WATCHDOG TIMER BLOCK DIAGRAM

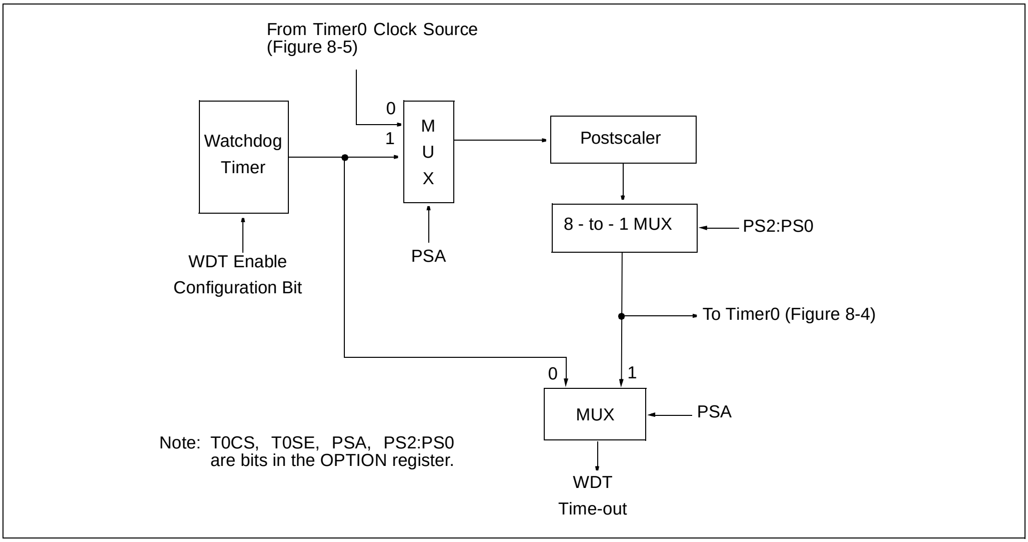


TABLE 8-6: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on All Other Resets
N/A	OPTION	$\overline{GPWU}$	$\overline{GPPU}$	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: Shaded boxes = Not used by Watchdog Timer, – = unimplemented, read as '0', u = unchanged

8.12 In-Circuit Serial Programming

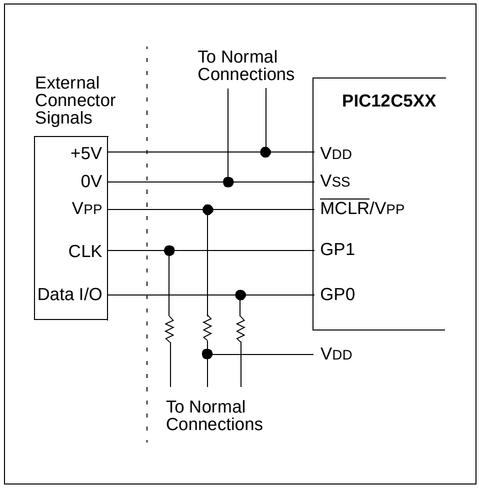
The PIC12C5XX microcontrollers with EPROM program memory can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the GP1 and GP0 pins low while raising the $\overline{MCLR}$ (V_{PP}) pin from V_{IL} to V_{IHH} (see programming specification). GP1 becomes the programming clock and GP0 becomes the programming data. Both GP1 and GP0 are Schmitt Trigger inputs in this mode.

After reset, a 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC12C5XX Programming Specifications.

A typical in-circuit serial programming connection is shown in Figure 8-16.

FIGURE 8-16: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



CALL — Subroutine Call

Syntax: [*label*] CALL k

Operands: $0 \le k \le 255$

Operation: (PC) + 1 → Top of Stack;
k → PC<7:0>;
(STATUS<6:5>) → PC<10:9>;
0 → PC<8>

Status Affected: None

Encoding:

1001	kkkk	kkkk

Description: Subroutine call. First, return address (PC+1) is pushed onto the stack. The eight bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. `CALL` is a two cycle instruction.

Words: 1

Cycles: 2

Example: `HERE CALL THERE`

Before Instruction
PC = address (`HERE`)

After Instruction
PC = address (`THERE`)
TOS = address (`HERE + 1`)

CLRF — Clear f

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 31$

Operation: 00h → (f);
1 → Z

Status Affected: Z

Encoding:

0000	011f	ffff

Description: The contents of register 'f' are cleared and the Z bit is set.

Words: 1

Cycles: 1

Example: `CLRF FLAG_REG`

Before Instruction
FLAG_REG = 0x5A

After Instruction
FLAG_REG = 0x00
Z = 1

CLRW — Clear W

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W);
1 → Z

Status Affected: Z

Encoding:

0000	0100	0000

Description: The W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example: `CLRW`

Before Instruction
W = 0x5A

After Instruction
W = 0x00
Z = 1

CLRWDT — Clear Watchdog Timer

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT;
0 → WDT prescaler (if assigned);
1 → $\overline{TO}$;
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

0000	0000	0100

Description: The `CLRWDT` instruction resets the WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Example: `CLRWDT`

Before Instruction
WDT counter = ?

After Instruction
WDT counter = 0x00
WDT prescale = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

SLEEP **Enter SLEEP Mode**

Syntax:	[*label*] SLEEP
Operands:	None
Operation:	00h → WDT; 0 → WDT prescaler; 1 → $\overline{TO}$; 0 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$, GPWUF
Encoding:	`0000` `0000` `0011`
Description:	Time-out status bit ($\overline{TO}$) is set. The power down status bit ($\overline{PD}$) is cleared. GPWUF is unaffected. The WDT and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See section on SLEEP for more details.
Words:	1
Cycles:	1
Example:	`SLEEP`

SUBWF **Subtract W from f**

Syntax:	[*label*] SUBWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) – (W) → (dest)
Status Affected:	C, DC, Z
Encoding:	`0000` `10df` `ffff`
Description:	Subtract (2's complement method) the W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.
Words:	1
Cycles:	1

Example 1: `SUBWF REG1, 1`

Before Instruction
REG1 = 3
W = 2
C = ?

After Instruction
REG1 = 1
W = 2
C = 1 ; result is positive

Example 2:

Before Instruction
REG1 = 2
W = 2
C = ?

After Instruction
REG1 = 0
W = 2
C = 1 ; result is zero

Example 3:

Before Instruction
REG1 = 1
W = 2
C = ?

After Instruction
REG1 = FF
W = 2
C = 0 ; result is negative

11.4 Timing Diagrams and Specifications

FIGURE 11-2: EXTERNAL CLOCK TIMING - PIC12C508/C509

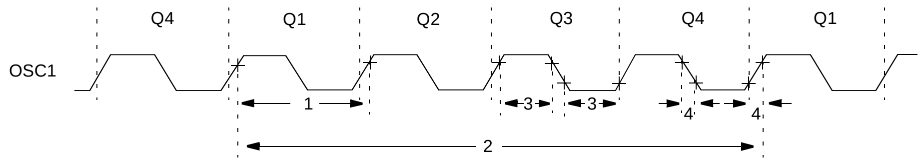


TABLE 11-2: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC12C508/C509

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C (commercial), –40°C ≤ TA ≤ +85°C (industrial), –40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in Section 11.1						
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	FOSC	External CLKIN Frequency(2)	DC	—	4	MHz	XT osc mode
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency(2)	0.1	—	4	MHz	XT osc mode
			DC	—	200	kHz	LP osc mode
1	TOSC	External CLKIN Period(2)	250	—	—	ns	EXTRC osc mode
			250	—	—	ns	XT osc mode
			5	—	—	ms	LP osc mode
		Oscillator Period(2)	250	—	—	ns	EXTRC osc mode
			250	—	10,000	ns	XT osc mode
			5	—	—	ms	LP osc mode
2	TCY	Instruction Cycle Time(3)	—	4/FOSC	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	—	—	ns	XT oscillator
			2*	—	—	ms	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

3: Instruction cycle period (TCY) equals four times the input oscillator time base period.

13.6 Timing Diagrams and Specifications

FIGURE 13-2: EXTERNAL CLOCK TIMING - PIC12C508A, PIC12C509A, PIC12CR509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

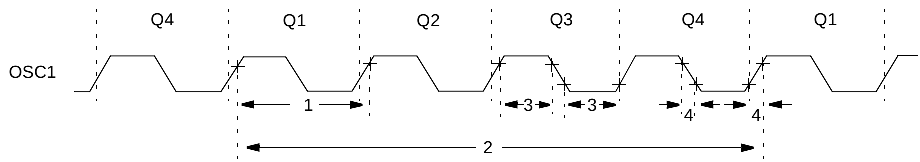


TABLE 13-2: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C (commercial), –40°C ≤ TA ≤ +85°C (industrial), –40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in Section 13.1						
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	FOSC	External CLKIN Frequency(2)					
			DC	—	4	MHz	XT osc mode
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency(2)	DC	—	4	MHz	EXTRC osc mode
			0.1	—	4	MHz	XT osc mode
			DC	—	200	kHz	LP osc mode
1	TOSC	External CLKIN Period(2)					
			250	—	—	ns	XT osc mode
			5	—	—	ms	LP osc mode
		Oscillator Period(2)	250	—	—	ns	EXTRC osc mode
			250	—	10,000	ns	XT osc mode
			5	—	—	ms	LP osc mode
2	Tcy	Instruction Cycle Time(3)	—	4/FOSC	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	—	—	ns	XT oscillator
			2*	—	—	ms	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

3: Instruction cycle period (TCY) equals four times the input oscillator time base period.

TABLE 13-6: DRT (DEVICE RESET TIMER PERIOD) - PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

Oscillator Configuration	POR Reset	Subsequent Resets
IntRC & ExtRC	18 ms (typical)[(1)]	300 µs (typical)[(1)]
XT & LP	18 ms (typical)[(1)]	18 ms (typical)[(1)]

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-5: TIMER0 CLOCK TIMINGS - PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

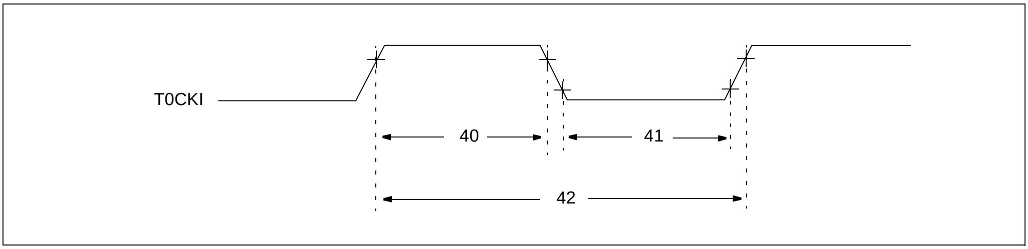


TABLE 13-7: TIMER0 CLOCK REQUIREMENTS - PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

AC Characteristics			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C (commercial) –40°C ≤ TA ≤ +85°C (industrial) –40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in Section 13.1.				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ[(1)]**	**Max**	**Units**	**Conditions**
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width - No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period	20 or (TCY + 40)/N*	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NOTES:

FIGURE 14-9: IOL vs. VOL, VDD = 2.5 V

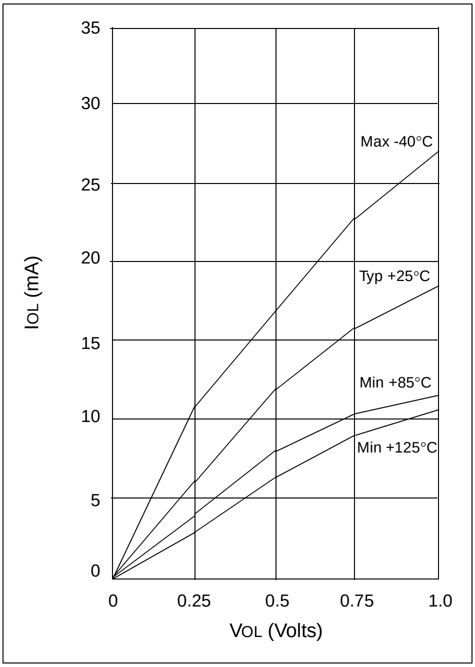


FIGURE 14-10: IOL vs. VOL, VDD = 3.5 V

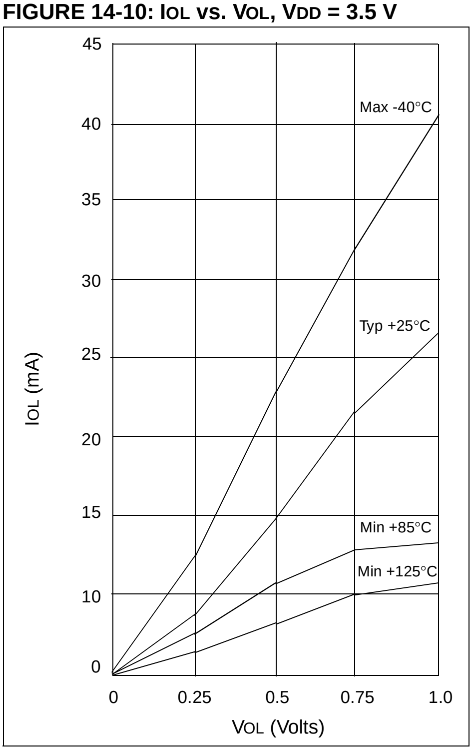


FIGURE 14-11: IOH vs. VOH, VDD = 5.5 V

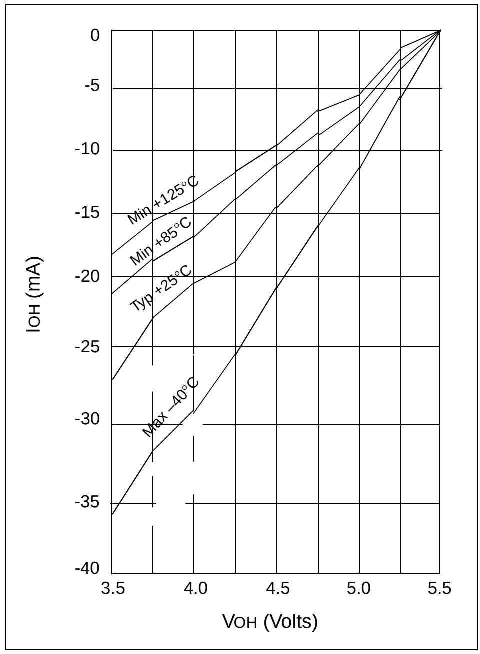


FIGURE 14-12: IOL vs. VOL, VDD = 5.5 V

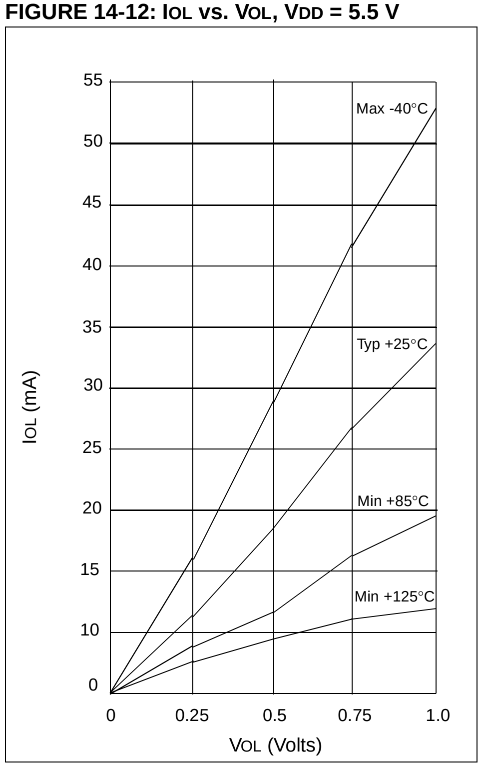


FIGURE 14-13: TYPICAL IPD VS. VDD, WATCHDOG DISABLED (25°C)

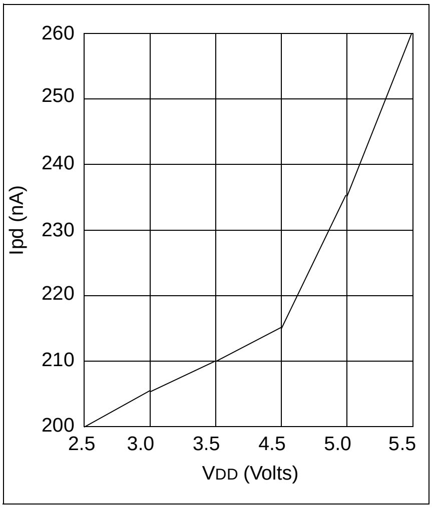
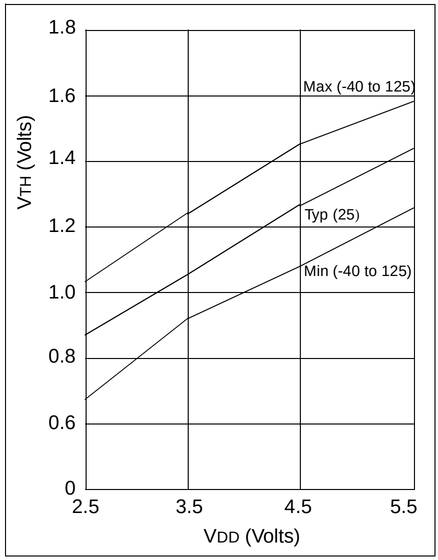


FIGURE 14-14: VTH (INPUT THRESHOLD VOLTAGE) OF GPIO PINS VS. VDD



15.0 PACKAGING INFORMATION

15.1 Package Marking Information

8-Lead PDIP (300 mil)

```
XXXXXXXX
XXXXXCDE
AABB
```

Example

```
12C508A
04I/PSAZ
9825
```

8-Lead SOIC (150 mil)

```
XXXXXXX
AABB
```

Example

```
C508A
9825
```

8-Lead SOIC (208 mil)

```
XXXXXXX
XXXXXXX
AABBCDE
```

Example

```
12C508A
04I/SM
9824SAZ
```

8-Lead Windowed Ceramic Side Brazed (300 mil)

```
XXX
XXXXXX
```

Example

```
JW
12C508A
```

Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calendar year)
	BB	Week code (week of January 1 is week '01')
	C	Facility code of the plant at which wafer is manufactured O = Outside Vendor C = 5" Line S = 6" Line H = 8" Line
	D	Mask revision number
	E	Assembly code of the plant or country of origin in which part was assembled

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask rev#, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

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